

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("6595506").PN.	US-PGPUB; USPAT	OR	OFF	2006/06/27 07:58
L11	0	(118/715-733.cds. 156/345\$.cds.) and (quasam)	US-PGPUB; USPAT	OR	ON	2006/06/27 08:12
L12	0	(quasam) same support\$3 same (substrate semiconductor wafer workpiece)	US-PGPUB; USPAT	OR	ON	2006/06/27 08:13
L13	4	(quasam)	US-PGPUB; USPAT	OR	ON	2006/06/27 08:21
L14	1	10/247,999	US-PGPUB; USPAT	OR	ON	2006/06/27 08:21
L15	2	10/247,499	US-PGPUB; USPAT	OR	ON	2006/06/27 08:21
L23	9	("5952060").URPN.	USPAT	OR	ON	2006/06/27 08:30
L24	37	("4340462" "4491496" "4534816" "4612077" "4948458" "5006200" "5022979" "5200232" "5262029" "5268200" "5308661" "5366585" "5393572" "5494713" "5522932" "5569356" "5641375" "5680013" "5798016" "5812362" "5820723" "5824605" "5838529" "5846613" "5863376" "5879523" "5885356" "5888907" "5891253" "5895586" "5904778" "5916370" "5952060" "5989511" "6015597" "6048798" "6071828").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/27 08:34
L25	1	24 and (dilyn dln)	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/27 08:34
L26	11	("6015597").URPN.	USPAT	OR	ON	2006/06/27 08:35
L27	75	(US-20030047283-\$ or US-20050183669-\$ or US-20050252454-\$ or US-20060075969-\$ or US-20050045106-\$ or US-20040244695-\$ or US-20040055709-\$ or US-20030069632-\$ or US-20040018749-\$ or US-20030168168-\$ or US-20050022746-\$ or US-20030162314-\$ or US-20050163985-\$).did. or (US-6228471-\$ or US-5352493-\$ or US-6508911-\$ or US-5508071-\$ or US-6579833-\$ or US-5695565-\$ or US-5507874-\$ or US-5638251-\$ or US-H000566-\$ or US-5786068-\$ or US-5728465-\$ or US-6998636-\$ or US-6472062-\$ or US-6200675-\$ or US-7019399-\$ or US-6669996-\$ or US-6468642-\$ or US-6696157-\$ or US-5763851-\$ or US-5466431-\$ or US-5718976-\$ or US-5795648-\$ or US-4886565-\$ or US-6753507-\$ or US-6749729-\$ or US-5711814-\$).did. or (US-6595506-\$ or US-6256187-\$ or US-6135054-\$ or US-5935323-\$ or US-5812362-\$ or US-5583736-\$ or US-5166856-\$ or US-5952060-\$ or US-6537429-\$ or US-6015597-\$ or US-6551718-\$ or US-5820723-\$ or US-5846613-\$ or US-5989511-\$).did. or (WO-9712757-\$ or WO-9640446-\$ or WO-9639943-\$ or WO-2005054539-\$ or WO-9641034-\$ or WO-9833948-\$ or EP-856592-\$ or WO-9740207-\$).did. or (JP-01167211-\$ or JP-2002246455-\$ or JP-06348154-\$ or JP-06025856-\$).did. or (DE-1004004177-\$ or WO-200159175-\$ or WO-2005054539-\$ or US-5466431-\$ or WO-2005054540-\$ or US-5352493-\$ or JP-01167211-\$ or US-5786068-\$ or EP-856592-\$ or JP-10096082-\$).did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/06/27 08:44
L28	21	27 and titanium	US-PGPUB; USPAT	OR	ON	2006/06/27 09:01
L29	0	"2004055709"	US-PGPUB; USPAT	OR	ON	2006/06/27 09:01

EAST Search History

L30	1	"20040055709"	US-PGPUB; USPAT	OR	ON	2006/06/27 09:42
L31	26	parkhe-vijay.in. ahmann-kurt.in. tsai-matthew.in. sansoni-steve.in.	US-PGPUB; USPAT	OR	ON	2006/06/27 09:42
S7	6	((("6493629") or ("6340928") or ("6674403") or ("5977913") or ("6850735") or ("6714605")).PN.	US-PGPUB; USPAT	OR	OFF	2006/06/13 20:32
S8	3	((("5354381") or ("5572038") or ("5911832")).PN.	US-PGPUB; USPAT	OR	OFF	2006/03/23 16:23
S9	1	("6747464").PN.	US-PGPUB; USPAT	OR	OFF	2006/03/23 16:23
S10	0	(118/715-733.ccls. 156/345\$.ccls.) and (carbon same diamond same network same support\$3)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:17
S11	0	((carbon with hydrogen with network) same support\$3 same (substrate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2006/06/13 20:35
S12	0	((carbon with hydrogen with network) same support\$3 same (substrate semiconductor wafer workpiece))	EPO; JPO; DERWENT	OR	ON	2006/06/13 20:35
S13	0	((carbon with hydrogen) same support\$3 same (substrate semiconductor wafer workpiece))	EPO; JPO; DERWENT	OR	ON	2006/06/13 20:34
S14	0	((carbon with hydrogen) same support\$3 same (substrate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2006/06/27 08:13
S15	801	((carbon with hydrogen) same support\$3 same (substrate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2006/06/13 20:34
S16	2	(118/715-733.ccls. 156/345\$.ccls.) and (carbon same diamond same network same support\$3)	US-PGPUB; USPAT	OR	ON	2006/06/13 20:43
S17	2	((carbon with hydrogen with network) same support\$3 same (substrate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2006/06/13 20:35
S18	2	((carbon with hydrogen with network) same support\$3 same (substrate semiconductor wafer workpiece))	EPO; JPO; DERWENT	OR	ON	2006/06/13 20:35
S19	801	((carbon with hydrogen) same support\$3 same (substrate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2006/06/13 20:48
S20	39	(diamond same (carbon with hydrogen) same support\$3 same (substrate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2006/06/13 20:36
S21	2	S20 and nanocomposite	US-PGPUB; USPAT	OR	ON	2006/06/13 20:36
S22	8	S15 and nanocomposite	US-PGPUB; USPAT	OR	ON	2006/06/13 20:36
S23	36	(118/715-733.ccls. 156/345\$.ccls.) and (carbon same diamond same support\$3)	US-PGPUB; USPAT	OR	ON	2006/06/13 20:43
S24	3	((carbon with hydrogen) same support\$3 same (substrate semiconductor wafer workpiece) same friction same hardness)	US-PGPUB; USPAT	OR	ON	2006/06/13 20:46
S25	1	((carbon with hydrogen) same support\$3 same (substrate semiconductor wafer workpiece) same friction same hardness)	EPO; JPO; DERWENT	OR	ON	2006/06/13 20:46
S26	1	((carbon with hydrogen) same support\$3 same friction same hardness)	EPO; JPO; DERWENT	OR	ON	2006/06/13 20:46
S27	2	((carbon with diamond) same support\$3 same friction same hardness)	EPO; JPO; DERWENT	OR	ON	2006/06/13 20:46
S28	44	((carbon same hydrogen same silicon same oxygen) same support\$3 same (substrate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2006/06/13 20:48
S29	1	((carbon same hydrogen same silicon same oxygen same composite) same support\$3 same (substrate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2006/06/13 20:48
S30	6	S28 and diamond	US-PGPUB; USPAT	OR	ON	2006/06/13 20:48
S31	0	("2003/0047283").URPN.	USPAT	OR	ON	2006/06/13 21:00

EAST Search History

S32	636	bekaert	US-PGPUB; USPAT	OR	ON	2006/06/13 21:00
S33	40	bekaert and (diamond)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:00
S34	40	bekaert and (diamond diamond\$1like)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:01
S35	2	("6200675").URPN.	USPAT	OR	ON	2006/06/13 21:03
S36	0	("6669996").URPN.	USPAT	OR	ON	2006/06/13 21:04
S37	0	("6669996").URPN.	USPAT	OR	ON	2006/06/13 21:04
S38	2	("6200675").URPN.	USPAT	OR	ON	2006/06/13 21:04
S39	0	(118/715-733.ccls. 156/345.\$ccls.) and (cdylyn)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:08
S40	0	(118/715-733.ccls. 156/345.\$ccls.) and (dylyn)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:08
S41	31	(dylyn)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:08
S42	0	(118/715-733.ccls. 156/345.\$ccls.) and (S41)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:08
S43	7	(S41) and (support\$3 with (substrate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2006/06/13 21:09
S44	0	(delryn) and (support\$3 with (substrate semiconductor wafer workpiece))	EPO; JPO; DERWENT	OR	ON	2006/06/13 21:09
S45	0	(dylyn) and (support\$3 with (substrate semiconductor wafer workpiece))	EPO; JPO; DERWENT	OR	ON	2006/06/13 21:10
S46	0	(dln) and (support\$3 with (substrate semiconductor wafer workpiece))	EPO; JPO; DERWENT	OR	ON	2006/06/13 21:11
S47	0	(belaert) and (support\$3 with (substrate semiconductor wafer workpiece))	EPO; JPO; DERWENT	OR	ON	2006/06/13 21:11
S48	2	(bekaert) and (support\$3 with (substrate semiconductor wafer workpiece))	EPO; JPO; DERWENT	OR	ON	2006/06/13 21:11
S49	420	(118/715-733.ccls. 156/345.\$ccls.) and (carbon same (diamond diamond\$1like) support\$3)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:17
S50	9617	(118/715-733.ccls. 156/345.\$ccls.) and (carbon same (diamond diamond\$1like) support\$3)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:17
S51	36	(118/715-733.ccls. 156/345.\$ccls.) and (carbon same (diamond diamond\$1like)same support\$3)	US-PGPUB; USPAT	OR	ON	2006/06/13 21:18
S52	1034	(shield\$3 lin\$3) with (provid\$3 cover\$3 protect\$3) with (bottom) with chamber	US-PGPUB; USPAT	OR	ON	2006/06/14 09:21
S53	70	(118/715-733.ccls. 156/345.\$ccls.) and ((shield\$3 lin\$3) with (provid\$3 cover\$3 protect\$3) with (bottom) with chamber)	US-PGPUB; USPAT	OR	ON	2006/06/14 09:21
S54	55	(118/715-733.ccls. 156/345.\$ccls.) and ((shield shielding liner) with (provid\$3 cover\$3 protect\$3) with (bottom) with chamber)	US-PGPUB; USPAT	OR	ON	2006/06/14 09:31
S55	9	(118/715-733.ccls. 156/345.\$ccls.) and ((inner\$1chamber sub\$1chamber) with (liner shield))	US-PGPUB; USPAT	OR	ON	2006/06/14 09:32
S56	2	((("5352493") or ("5466431"))).PN.	US-PGPUB; USPAT	OR	OFF	2006/06/15 17:46
S57	44	("5466431").URPN.	USPAT	OR	ON	2006/06/15 17:48
S58	9	S57 and susceptor	US-PGPUB; USPAT	OR	ON	2006/06/15 17:49
S59	0	dln with susceptor	US-PGPUB; USPAT	OR	ON	2006/06/15 17:49
S60	0	dln with susceptor	EPO; JPO; DERWENT	OR	ON	2006/06/15 17:49

EAST Search History

S61	3	dln and (118/728-732.cds. 156/345.51-345.54.cds.)	US-PGPUB; USPAT	OR	ON	2006/06/15 17:51
S62	961	dln	US-PGPUB; USPAT	OR	ON	2006/06/15 17:50
S63	3	dln and (118/728-732.cds. 156/345.51-345.55.cds.)	US-PGPUB; USPAT	OR	ON	2006/06/15 18:01
S64	178	dln and ((substrate wafer semiconductor substrate) same (support\$4 hold\$4 table susceptor))	US-PGPUB; USPAT	OR	ON	2006/06/15 17:53
S65	123	dln and ((substrate wafer semiconductor substrate) with (support\$4 hold\$4 table susceptor))	US-PGPUB; USPAT	OR	ON	2006/06/15 17:52
S66	9	dln same((substrate wafer semiconductor substrate) with (support\$4 hold\$4 table susceptor))	US-PGPUB; USPAT	OR	ON	2006/06/15 17:52
S67	0	dln and ((substrate wafer semiconductor substrate) same (support\$4 hold\$4 table susceptor))	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:20
S68	0	dln and ((substrate wafer semiconductor substrate) and (support\$4 hold\$4 table susceptor))	EPO; JPO; DERWENT	OR	ON	2006/06/15 17:54
S69	2	dln and ((support\$4 hold\$4 table susceptor))	EPO; JPO; DERWENT	OR	ON	2006/06/15 17:54
S70	7	diamond and nanocomposite and ((support\$4 hold\$4 table susceptor))	EPO; JPO; DERWENT	OR	ON	2006/06/15 17:56
S71	17	diamond and nanocomposite and (substrate wafer)	EPO; JPO; DERWENT	OR	ON	2006/06/15 17:56
S72	5	(diamond\$5 with carbon with \$5composite) and (118/728-732.cds. 156/345.51-345.55.cds.)	US-PGPUB; USPAT	OR	ON	2006/06/15 18:00
S73	6	(diamond\$5 with carbon with \$5composite) and (susceptor)	US-PGPUB; USPAT	OR	ON	2006/06/15 18:00
S74	83	(diamond same carbon) and (118/728-732.cds. 156/345.51-345.55.cds.)	US-PGPUB; USPAT	OR	ON	2006/06/15 18:24
S75	70	(diamond with carbon) and (118/728-732.cds. 156/345.51-345.55.cds.)	US-PGPUB; USPAT	OR	ON	2006/06/15 18:14
S76	7	"269"/\$.cds. and (diamond with carbon)	US-PGPUB; USPAT	OR	ON	2006/06/15 18:15
S77	5	("6595506").URPN.	USPAT	OR	ON	2006/06/15 18:16
S78	0	("6595506").URPN. and diamond	USPAT	OR	ON	2006/06/15 18:16
S79	0	("6595506").URPN. and diamond\$5	USPAT	OR	ON	2006/06/15 18:16
S80	0	S77 and diamond\$5	USPAT	OR	ON	2006/06/15 18:16
S81	12	("5166856" "5324012" "5583736" "5707409" "5812362" "5924917" "5935323" "5989693" "6086796" "6135054" "6256187" "6316734").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/15 18:17
S82	2	"01167211"	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:20
S83	305	(diamond\$5 with carbon) and ((substrate wafer semiconductor substrate) same (support\$4 hold\$4 table susceptor))	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:24
S84	283	(diamond\$5 with carbon) and ((substrate wafer semiconductor substrate) with (support\$4 hold\$4 table susceptor))	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:25
S85	170	(diamond\$5 with carbon) same ((substrate wafer semiconductor substrate) with (support\$4 hold\$4 table susceptor))	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:25
S86	68	("diamond-like" with carbon) same ((substrate wafer semiconductor substrate) with (support\$4 hold\$4 table susceptor))	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:25
S87	72	(diamond\$1like with carbon) same ((substrate wafer semiconductor substrate) with (support\$4 hold\$4 table susceptor))	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:37

EAST Search History

S88	35	(diamond\$1like with carbon) same ((substrate wafer semiconductor substrate) with (support\$4 hold\$4 table susceptor chuck electrostatic "esc" clamp)) same (protect\$4 prohibit\$4 wear resist\$4 hard\$4 friction\$4 elas\$7 abras\$5)	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:28
S89	1	("5952060").PN.	US-PGPUB; USPAT	OR	OFF	2006/06/15 18:34
S90	1	(diamond\$1like with carbon with nano\$1composite) and electrostatic	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:38
S91	6	(diamond\$1like with carbon with nano\$1composite) and electrostatic	US-PGPUB; USPAT	OR	ON	2006/06/15 18:39
S92	9	(diamond\$1like with nano\$1composite) and electrostatic	US-PGPUB; USPAT	OR	ON	2006/06/15 18:41
S93	10	(diamond\$1like with nano\$1composite) and electrostatic\$5	US-PGPUB; USPAT	OR	ON	2006/06/15 18:41
S94	1	S93 not S92	US-PGPUB; USPAT	OR	ON	2006/06/15 18:41
S95	1	(diamond\$1like with nano\$1composite) and electrostatic\$5	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:42
S96	5	"856592"	EPO; JPO; DERWENT	OR	ON	2006/06/15 18:42
S97	2	((("5352493") or ("6228471"))).PN.	US-PGPUB; USPAT	OR	OFF	2006/06/26 17:00
S98	1	("20030047283").PN.	US-PGPUB; USPAT	OR	OFF	2006/06/26 17:00